



PCA9554B; PCA9554C

Low-voltage 8-bit I²C-bus and SMBus low power I/O port with interrupt, weak pull-up

Rev. 1 — 19 September 2012

Product data sheet

1. General description

The PCA9554B and PCA9554C are low-voltage 8-bit General Purpose Input/Output (GPIO) expanders with interrupt for I²C-bus/SMBus applications. The only difference between the PCA9554B and PCA9554C is their I²C fixed address allowing a larger number of the same device on the I²C-bus with no chance of address conflict. NXP I/O expanders provide a simple solution when additional I/Os are needed while keeping interconnections to a minimum, for example, in ACPI power switches, sensors, push buttons, LEDs, fan control, etc.

In addition to providing a flexible set of GPIOs, the wide V_{DD} range of 1.65 V to 5.5 V allow the PCA9554B/PCA9554C to interface with next-generation microprocessors and microcontrollers where supply levels are dropping down to conserve power.

The PCA9554B/PCA9554C contain a register set of 8-bit Configuration, Input, Output, and Polarity Inversion registers.

The PCA9554B is a pin-to-pin replacement for the PCA9554, while the PCA9554C replaces the PCA9554A. Both of these devices replace other industry-standard part numbers. More fully-featured parts PCAL9554B and PCAL9554C are also available with Agile I/O features. See the respective data sheet for more details.

The PCA9554B/PCA9554C open-drain interrupt ($\overline{\text{INT}}$) output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system master that an input state has changed.

$\overline{\text{INT}}$ can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I²C-bus. Thus, the PCA9554B/PCA9554C can remain a simple slave device.

The device outputs have 25 mA sink capabilities for directly driving LEDs while consuming low device current.

The power-on reset sets the registers to their default values and initializes the device state machine.

Three hardware pins (A0, A1, A2) select the fixed I²C-bus address and allow up to eight devices to share the same I²C-bus/SMBus. The PCA9554B and PCA9554C differ only in their base I²C-bus addresses permitting a total of 16 devices on the I²C-bus, minimizing the chance for address conflict, even in the most complex system.



2. Features and benefits

- I²C-bus to parallel port expander
- Operating power supply voltage range of 1.65 V to 5.5 V
- Low standby current consumption:
 - ◆ 1.5 μ A (typical at 5 V V_{DD})
 - ◆ 1.0 μ A (typical at 3.3 V V_{DD})
- Schmitt-trigger action allows slow input transition and better switching noise immunity at the SCL and SDA inputs
 - ◆ $V_{hys} = 0.10 \times V_{DD}$ (typical)
- 5 V tolerant I/Os
- Open-drain active LOW interrupt output (\overline{INT})
- 400 kHz Fast-mode I²C-bus
- Input/output configuration register
- Polarity inversion register
- Internal power-on reset
- Power-up with all channels configured as inputs
- No glitch on power-up
- Latched outputs with 25 mA drive maximum capability for directly driving LEDs
- Latch-up performance exceeds 100 mA per JESD78, Class II
- ESD protection exceeds JESD22
 - ◆ 2000 V Human Body Model (A114-A)
 - ◆ 1000 V Charged-Device Model (C101)
- Packages offered: TSSOP16 and HVQFN16

3. Ordering information

Table 1. Ordering information

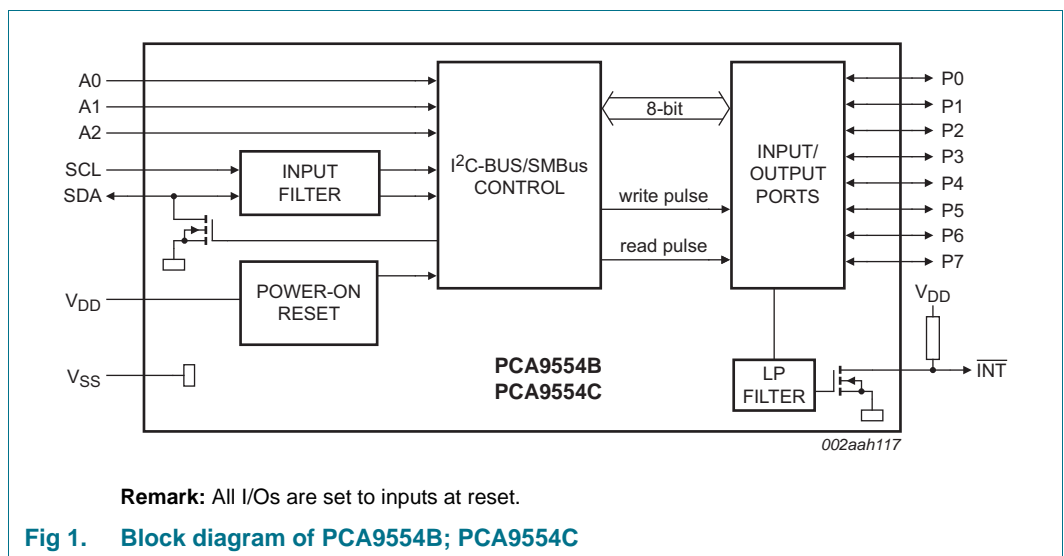
| Type number | Topside mark | Package | | Version |
|-------------|--------------|---------|--|----------|
| | | Name | Description | |
| PCA9554BBS | P4B | HVQFN16 | plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 × 3 × 0.85 mm | SOT758-1 |
| PCA9554BPW | PA9554B | TSSOP16 | plastic thin shrink small outline package; 16 leads; body width 4.4 mm | SOT403-1 |
| PCA9554CBS | P4C | HVQFN16 | plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 × 3 × 0.85 mm | SOT758-1 |
| PCA9554CPW | PA9554C | TSSOP16 | plastic thin shrink small outline package; 16 leads; body width 4.4 mm | SOT403-1 |

3.1 Ordering options

Table 2. Ordering options

| Type number | Orderable part number | Package | Packing method | Minimum order quantity | Temperature range |
|-------------|-----------------------|---------|---------------------------------|------------------------|-------------------------------------|
| PCA9554BBS | PCA9554BBSHP | HVQFN16 | Reel pack, SMD, 13-inch, Turned | 6000 | T _{amb} = -40 °C to +85 °C |
| PCA9554BPW | PCA9554BPWJ | TSSOP16 | Reel pack, SMD, 13-inch | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9554CBS | PCA9554CBSHP | HVQFN16 | Reel pack, SMD, 13-inch, Turned | 6000 | T _{amb} = -40 °C to +85 °C |
| PCA9554CPW | PCA9554CPWJ | TSSOP16 | Reel pack, SMD, 13-inch | 2500 | T _{amb} = -40 °C to +85 °C |

4. Block diagram



5. Pinning information

5.1 Pinning

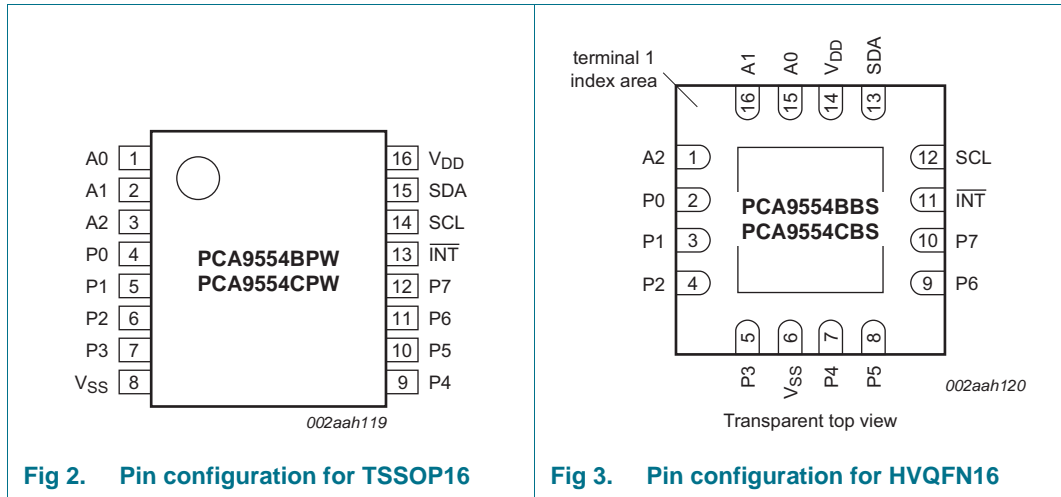


Fig 2. Pin configuration for TSSOP16

Fig 3. Pin configuration for HVQFN16

5.2 Pin description

Table 3. Pin description

| Symbol | Pin | | Description |
|-------------------------|---------|------------------|-------------------------------|
| | TSSOP16 | HVQFN16 | |
| A0 | 1 | 15 | address input 0 |
| A1 | 2 | 16 | address input 1 |
| A2 | 3 | 1 | address input 2 |
| P0 ^[1] | 4 | 2 | Port P input/output 0 |
| P1 ^[1] | 5 | 3 | Port P input/output 1 |
| P2 ^[1] | 6 | 4 | Port P input/output 2 |
| P3 ^[1] | 7 | 5 | Port P input/output 3 |
| V _{SS} | 8 | 6 ^[2] | supply ground |
| P4 ^[1] | 9 | 7 | Port P input/output 4 |
| P5 ^[1] | 10 | 8 | Port P input/output 5 |
| P6 ^[1] | 11 | 9 | Port P input/output 6 |
| P7 ^[1] | 12 | 10 | Port P input/output 7 |
| $\overline{\text{INT}}$ | 13 | 11 | interrupt output (open-drain) |
| SCL | 14 | 12 | serial clock line |
| SDA | 15 | 13 | serial data line |
| V _{DD} | 16 | 14 | supply voltage |

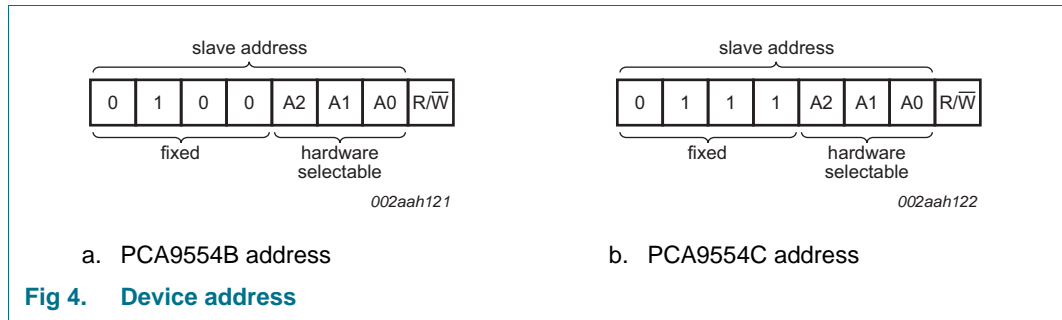
[1] All I/O are configured as input at power-on.

[2] HVQFN16 package die supply ground is connected to both the V_{SS} pin and the exposed center pad. The V_{SS} pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board-level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board, and for proper heat conduction through the board thermal vias need to be incorporated in the printed-circuit board in the thermal pad region.

6. Functional description

Refer to [Figure 1 “Block diagram of PCA9554B; PCA9554C”](#).

6.1 Device address



A2, A1 and A0 are the hardware address package pins and are held to either HIGH (logic 1) or LOW (logic 0) to assign one of the eight possible slave addresses. The last bit of the slave address (R/W) defines the operation (read or write) to be performed. A HIGH (logic 1) selects a read operation, while a LOW (logic 0) selects a write operation.

6.2 Pointer register and command byte

Following the successful acknowledgement of the address byte, the bus master sends a command byte, which is stored in the Pointer register in the PCA9554B/PCA9554C. Two bits of this data byte state the operation (read or write) and the internal registers (Input, Output, Polarity Inversion, or Configuration) that will be affected. This register is write only.

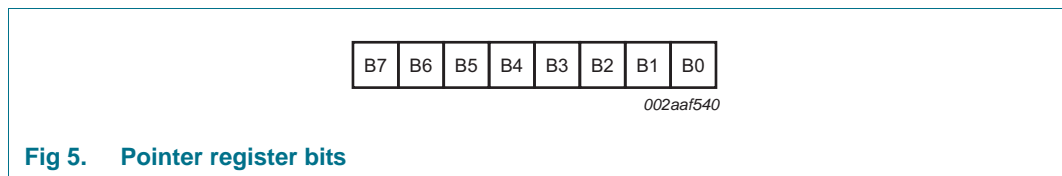


Table 4. Command byte

| Pointer register bits | | | | | | | | Command byte (hexadecimal) | Register | Protocol | Power-up default |
|-----------------------|----|----|----|----|----|----|----|----------------------------|--------------------|-----------------|--------------------------|
| B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 00h | Input port | read byte | xxxx xxxx ^[1] |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 01h | Output port | read/write byte | 1111 1111 |
| 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0 | 02h | Polarity Inversion | read/write byte | 0000 0000 |
| 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 | 03h | Configuration | read/write byte | 1111 1111 |

[1] Undefined.

6.3 Interface definition

Table 5. Interface definition

| Byte | Bit | | | | | | | |
|--|---------|----|----|----|----|----|----|-------------------|
| | 7 (MSB) | 6 | 5 | 4 | 3 | 2 | 1 | 0 (LSB) |
| PCA9554B I ² C-bus slave address | L | H | L | L | A2 | A1 | A0 | R/ \overline{W} |
| PCA9554C I ² C-bus slave address | L | H | H | H | A2 | A1 | A0 | R/ \overline{W} |
| I/O data bus | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |

6.4 Register descriptions

6.4.1 Input port register (00h)

The Input port register (register 0) reflects the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration register. The Input port register is read only; writes to this register have no effect. The default value 'X' is determined by the externally applied logic level. An Input port register read operation is performed as described in [Section 7.2 "Read commands"](#).

Table 6. Input port register (address 00h)

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|----|----|----|----|----|----|----|----|
| Symbol | I7 | I6 | I5 | I4 | I3 | I2 | I1 | I0 |
| Default | X | X | X | X | X | X | X | X |

6.4.2 Output port register (01h)

The Output port register (register 1) shows the outgoing logic levels of the pins defined as outputs by the Configuration register. Bit values in these registers have no effect on pins defined as inputs. In turn, reads from this register reflect the value that was written to this register, **not** the actual pin value.

Table 7. Output port register (address 01h)

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|----|----|----|----|----|----|----|----|
| Symbol | O7 | O6 | O5 | O4 | O3 | O2 | O1 | O0 |
| Default | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |

6.4.3 Polarity inversion register (02h)

The Polarity inversion register (register 2) allows polarity inversion of pins defined as inputs by the Configuration register. If a bit in this register is set (written with '1'), the corresponding port pin's polarity is inverted. If a bit in this register is cleared (written with a '0'), the corresponding port pin's original polarity is retained.

Table 8. Polarity inversion register (address 02h)

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|----|----|----|----|----|----|----|----|
| Symbol | N7 | N6 | N5 | N4 | N3 | N2 | N1 | N0 |
| Default | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

6.4.4 Configuration register (03h)

The Configuration register (register 3) configures the direction of the I/O pins. If a bit in this register is set to 1, the corresponding port pin is enabled as a high-impedance input. If a bit in this register is cleared to 0, the corresponding port pin is enabled as an output.

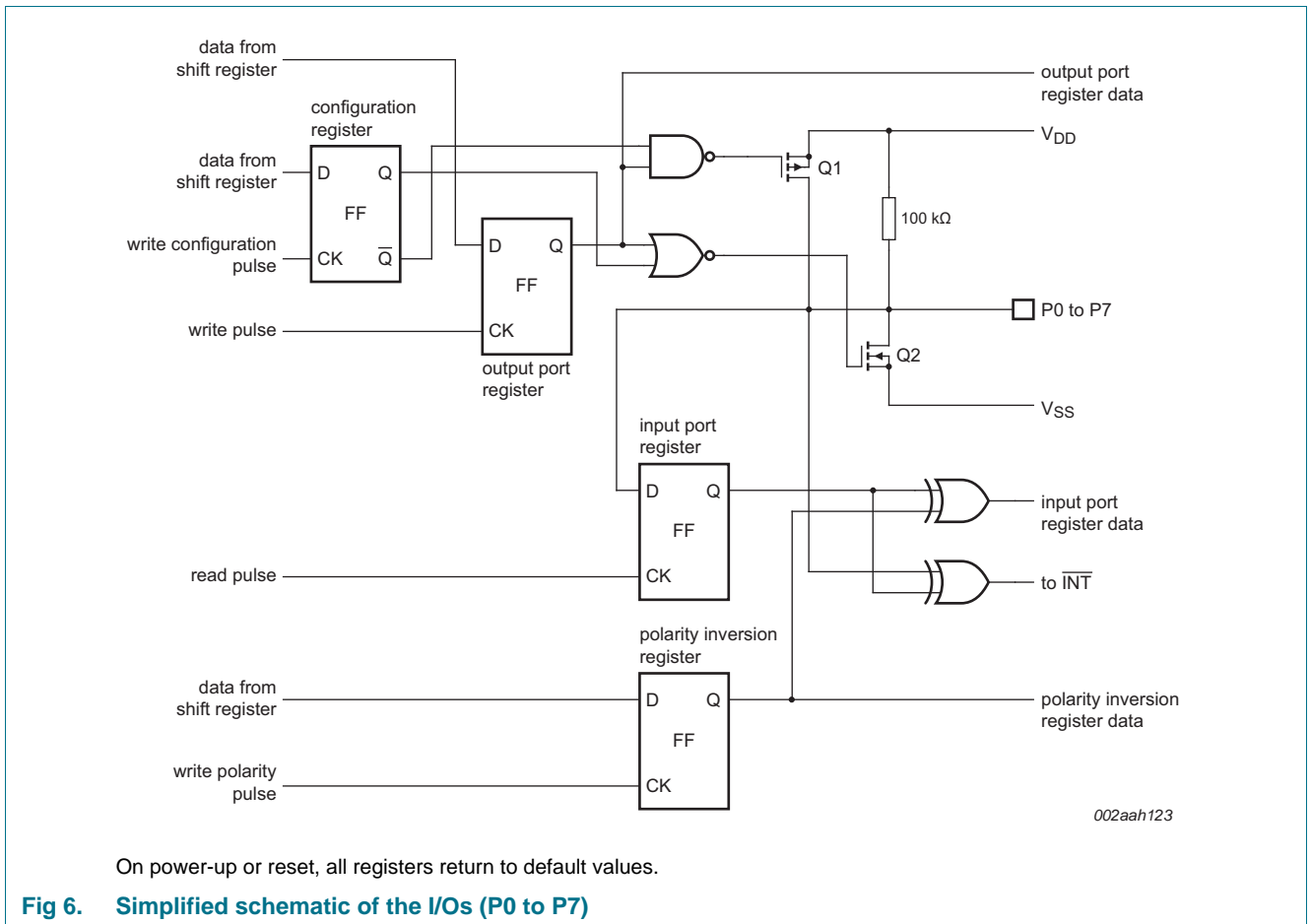
Table 9. Configuration register (address 03h)

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|----|----|----|----|----|----|----|----|
| Symbol | C7 | C6 | C5 | C4 | C3 | C2 | C1 | C0 |
| Default | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |

6.5 I/O port

When an I/O is configured as an input, FETs Q1 and Q2 are off, which creates a high-impedance input. The input voltage may be raised above V_{DD} to a maximum of 5.5 V.

If the I/O is configured as an output, Q1 or Q2 is enabled, depending on the state of the Output port register. In this case, there are low-impedance paths between the I/O pin and either V_{DD} or V_{SS}. The external voltage applied to this I/O pin should not exceed the recommended levels for proper operation.



6.6 Power-on reset

When power (from 0 V) is applied to V_{DD} , an internal power-on reset holds the PCA9554B/PCA9554C in a reset condition until V_{DD} has reached V_{POR} . At that time, the reset condition is released and the PCA9554B/PCA9554C registers and I²C-bus/SMBus state machine initialize to their default states. After that, V_{DD} must be lowered to below V_{PORF} and back up to the operating voltage for a power-reset cycle. See [Section 8.2](#) “Power-on reset requirements”.

6.7 Interrupt output (\overline{INT})

An interrupt is generated by any rising or falling edge of the port inputs in the Input mode. After time $t_{V(INT)}$, the signal \overline{INT} is valid. Resetting the interrupt circuit is achieved when data on the port is changed to the original setting or when data is read from the port that generated the interrupt (see [Figure 10](#)). Resetting occurs in the Read mode at the acknowledge (ACK) or not acknowledge (NACK) bit after the rising edge of the SCL signal. Interrupts that occur during the ACK or NACK clock pulse can be lost (or be very short) due to the reset of the interrupt during this pulse. Each change of the I/Os after resetting is detected and is transmitted as \overline{INT} .

A pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur, if the state of the pin does not match the contents of the Input port register.

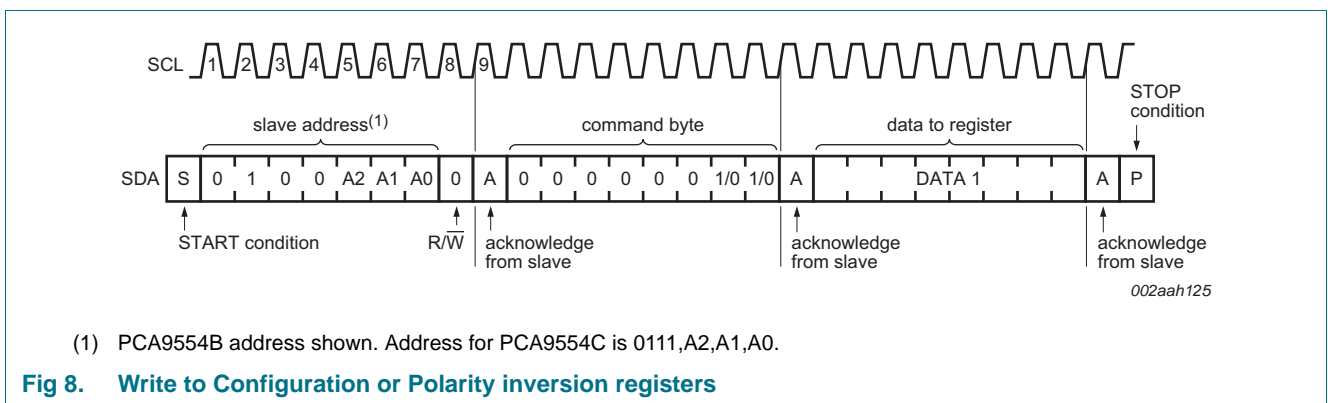
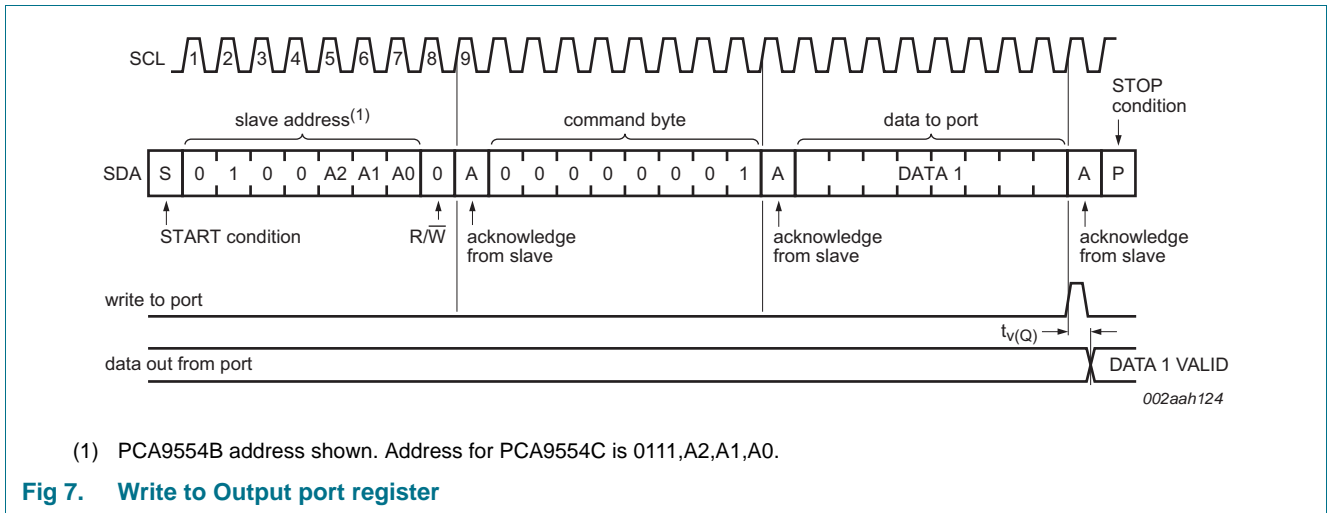
The \overline{INT} output has an open-drain structure and requires a pull-up resistor to V_{DD} . \overline{INT} should be connected to the voltage source of the device that requires the interrupt information. When using the input latch feature, the input pin state is latched. The interrupt is reset only when data is read from the port that generated the interrupt. The reset occurs in the Read mode at the acknowledge (ACK) or not acknowledge (NACK) bit after the rising edge of the SCL signal.

7. Bus transactions

The PCA9554B/PCA9554C is an I²C-bus slave device. Data is exchanged between the master and PCA9554B/PCA9554C through write and read commands using I²C-bus. The two communication lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

7.1 Write commands

Data is transmitted to the PCA9554B/PCA9554C by sending the device address and setting the Least Significant Bit (LSB) to a logic 0 (see Figure 4 for device address). The command byte is sent after the address and determines which register receives the data that follows the command byte. There is no limitation on the number of data bytes sent in one write transmission.



8. Application design-in information

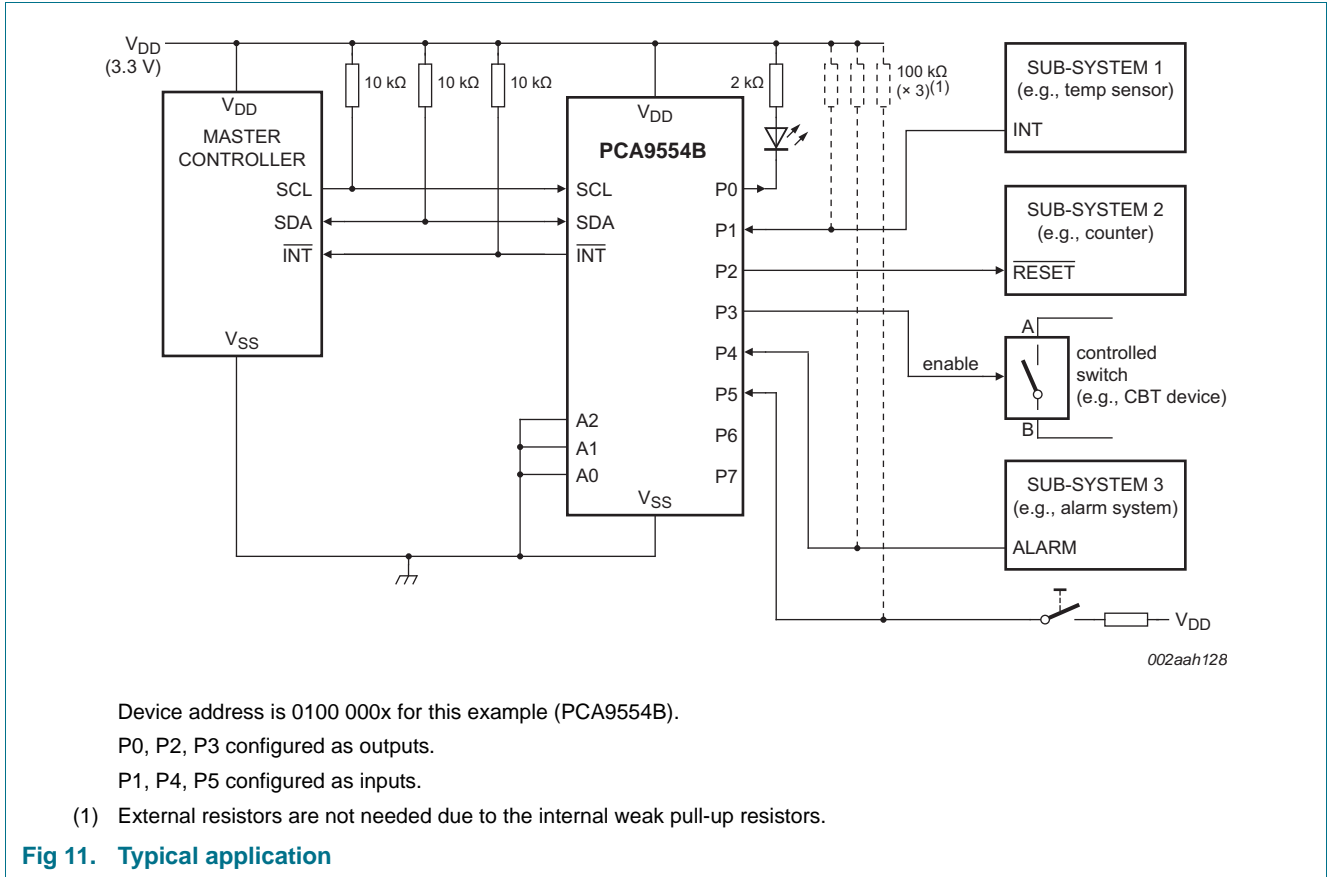
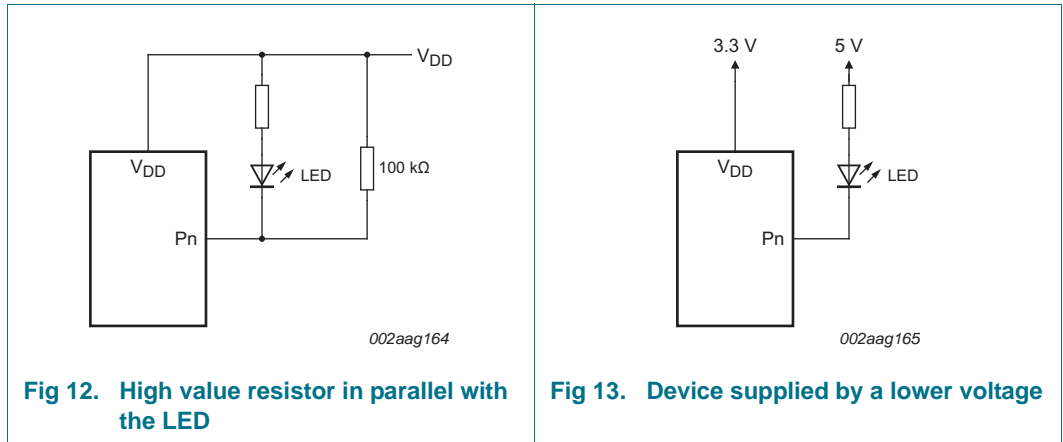


Fig 11. Typical application

8.1 Minimizing I_{DD} when the I/Os are used to control LEDs

When the I/Os are used to control LEDs, they are normally connected to V_{DD} through a resistor as shown in Figure 11. Since the LED acts as a diode, when the LED is off the I/O V_I is about 1.2 V less than V_{DD}. The supply current, I_{DD}, increases as V_I becomes lower than V_{DD}.

Designs needing to minimize current consumption, such as battery power applications, should consider maintaining the I/O pins greater than or equal to V_{DD} when the LED is off. Figure 12 and Figure 13 show typical solutions to minimizing current consumption. Figure 12 shows a high value resistor in parallel with the LED. Figure 13 shows V_{DD} less than the LED supply voltage by at least 1.2 V. However, the PCA9554B/PCA9554C needs no external resistors due to the integrated 100 kΩ pull-up resistors.



8.2 Power-on reset requirements

In the event of a glitch or data corruption, PCA9554B/PCA9554C can be reset to its default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

The two types of power-on reset are shown in [Figure 14](#) and [Figure 15](#).

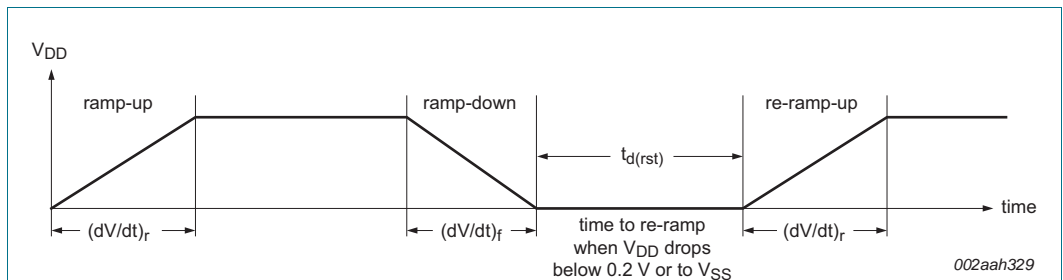


Fig 14. V_{DD} is lowered below 0.2 V or 0 V and then ramped up to V_{DD}

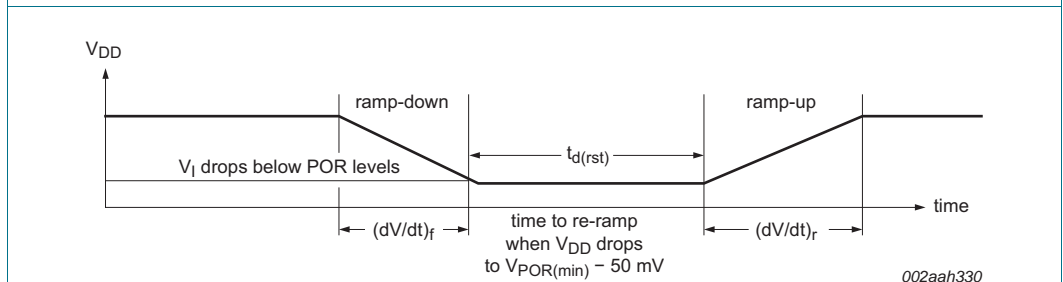


Fig 15. V_{DD} is lowered below the POR threshold, then ramped back up to V_{DD}

[Table 10](#) specifies the performance of the power-on reset feature for PCA9554B/PCA9554C for both types of power-on reset.

Table 10. Recommended supply sequencing and ramp rates
T_{amb} = 25 °C (unless otherwise noted). Not tested; specified by design.

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|------------------------|-----------------------------------|---|-----|-----|------|------|
| (dV/dt) _f | fall rate of change of voltage | Figure 14 | 0.1 | - | 2000 | ms |
| (dV/dt) _r | rise rate of change of voltage | Figure 14 | 0.1 | - | 2000 | ms |
| t _{d(rst)} | reset delay time | Figure 14; re-ramp time when V _{DD} drops to V _{SS} | 1 | - | - | μs |
| | | Figure 15; re-ramp time when V _{DD} drops to V _{POR(min)} - 50 mV | 1 | - | - | μs |
| ΔV _{DD(gl)} | glitch supply voltage difference | Figure 16 | [1] | - | 1.0 | V |
| t _{w(gl)VDD} | supply voltage glitch pulse width | Figure 16 | [2] | - | 10 | μs |
| V _{POR(trip)} | power-on reset trip voltage | falling V _{DD} | 0.7 | - | - | V |
| | | rising V _{DD} | - | - | 1.4 | V |

- [1] Level that V_{DD} can glitch down to with a ramp rate of 0.4 μs/V, but not cause a functional disruption when t_{w(gl)VDD} < 1 μs.
- [2] Glitch width that will not cause a functional disruption when ΔV_{DD(gl)} = 0.5 × V_{DD}.

Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width (t_{w(gl)VDD}) and glitch height (ΔV_{DD(gl)}) are dependent on each other. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. Figure 16 and Table 10 provide more information on how to measure these specifications.

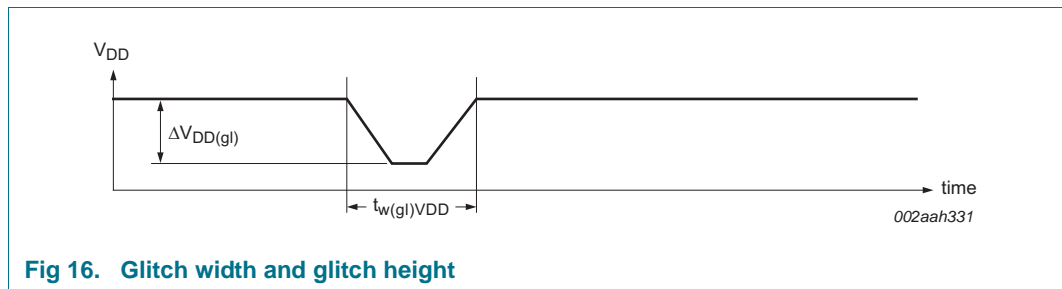


Fig 16. Glitch width and glitch height

V_{POR} is critical to the power-on reset. V_{POR} is the voltage level at which the reset condition is released and all the registers and the I²C-bus/SMBus state machine are initialized to their default states. The value of V_{POR} differs based on the V_{DD} being lowered to or from 0 V. Figure 17 and Table 10 provide more details on this specification.

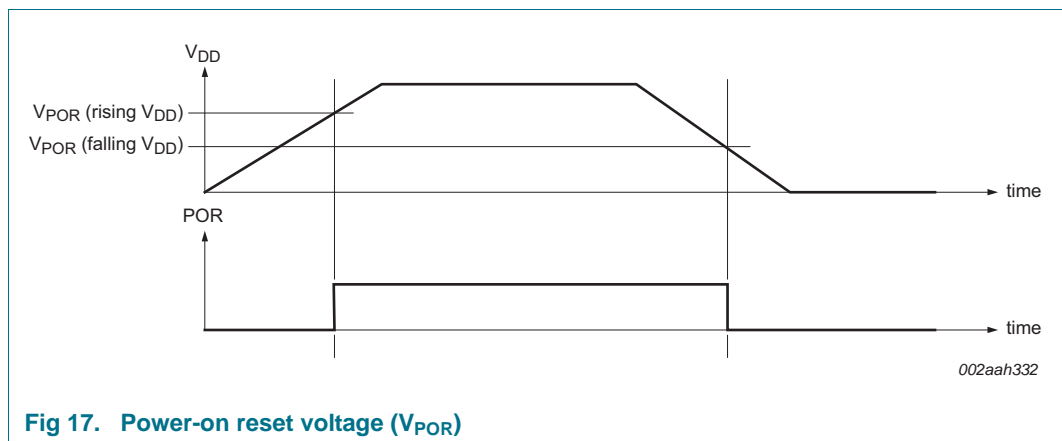


Fig 17. Power-on reset voltage (V_{POR})

8.3 Device current consumption with internal pull-up and pull-down resistors

The PCA9554B/PCA9554C integrates programmable pull-up and pull-down resistors to eliminate external components when pins are configured as inputs and pull-up or pull-down resistors are required (for example, nothing is driving the inputs to the power supply rails). Since these pull-up and pull-down resistors are internal to the device itself, they contribute to the current consumption of the device and must be considered in the overall system design.

The pull-up or pull-down function is selected in registers 48h and 49h, while the resistor is connected by the enable registers 46h and 47h. The configuration of the resistors is shown in [Figure 6](#).

If the resistor is configured as a pull-up, that is, connected to V_{DD} , a current will flow from the V_{DD} pin through the resistor to ground when the pin is held LOW. This current will appear as additional I_{DD} upsetting any current consumption measurements.

In the same manner, if the resistor is configured as a pull-down and the pin is held HIGH, current will flow from the power supply through the pin to the V_{SS} pin. While this current will not be measured as part of I_{DD} , one must be mindful of the 200 mA limiting value through V_{SS} .

The pull-up and pull-down resistors are simple resistors and the current is linear with voltage. The resistance specification for these devices spans from 50 k Ω with a nominal 100 k Ω value. Any current flow through these resistors is additive by the number of pins held HIGH or LOW and the current can be calculated by Ohm's law. See [Figure 21](#) for a graph of supply current versus the number of pull-up resistors.

9. Limiting values

Table 11. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---------------------|-------------------------------|--|----------|------|------|
| V _{DD} | supply voltage | | -0.5 | +6.5 | V |
| V _I | input voltage | | [1] -0.5 | +6.5 | V |
| V _O | output voltage | | [1] -0.5 | +6.5 | V |
| I _{IK} | input clamping current | A0, A1, A2, SCL; V _I < 0 V | - | ±20 | mA |
| I _{OK} | output clamping current | $\overline{\text{INT}}$; V _O < 0 V | - | ±20 | mA |
| I _{IOK} | input/output clamping current | P port; V _O < 0 V or V _O > V _{DD} | - | ±20 | mA |
| | | SDA; V _O < 0 V or V _O > V _{DD} | - | ±20 | mA |
| I _{OL} | LOW-level output current | continuous; I/O port | - | 50 | mA |
| | | continuous; SDA, $\overline{\text{INT}}$ | - | 25 | mA |
| I _{OH} | HIGH-level output current | continuous; P port | - | 25 | mA |
| I _{DD} | supply current | | - | 160 | mA |
| I _{SS} | ground supply current | | - | 200 | mA |
| P _{tot} | total power dissipation | | - | 200 | mW |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| T _{j(max)} | maximum junction temperature | | - | 125 | °C |

[1] The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

10. Recommended operating conditions

Table 12. Operating conditions

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|---------------------------|-----------------------|-----------------------|-----------------------|------|
| V _{DD} | supply voltage | | 1.65 | 5.5 | V |
| V _{IH} | HIGH-level input voltage | SCL, SDA | 0.7 × V _{DD} | 5.5 | V |
| | | A0, A1, A2, P port | 0.7 × V _{DD} | 5.5 | V |
| V _{IL} | LOW-level input voltage | SCL, SDA | -0.5 | 0.3 × V _{DD} | V |
| | | A0, A1, A2, P port | -0.5 | 0.3 × V _{DD} | V |
| I _{OH} | HIGH-level output current | P port | - | 10 | mA |
| I _{OL} | LOW-level output current | P port | - | 25 | mA |
| T _{amb} | ambient temperature | operating in free air | -40 | +85 | °C |

11. Thermal characteristics

Table 13. Thermal characteristics

| Symbol | Parameter | Conditions | Max | Unit |
|----------------------|--|-----------------|---------|------|
| Z _{th(j-a)} | transient thermal impedance from junction to ambient | HVQFN16 package | [1] 53 | K/W |
| | | TSSOP16 package | [1] 108 | K/W |

[1] The package thermal impedance is calculated in accordance with JESD 51-7.

12. Static characteristics

Table 14. Static characteristics
 $T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}; V_{DD} = 1.65\text{ V to }5.5\text{ V}; \text{ unless otherwise specified.}$

| Symbol | Parameter | Conditions | Min | Typ ^[1] | Max | Unit |
|--|---------------------------|--|--------------------|--------------------|------|------|
| V _{IK} | input clamping voltage | I _I = -18 mA | -1.2 | - | - | V |
| V _{POR} | power-on reset voltage | V _I = V _{DD} or V _{SS} ; I _O = 0 mA | - | 1.1 | 1.4 | V |
| I _{OL} | LOW-level output current | V _{OL} = 0.4 V; V _{DD} = 1.65 V to 5.5 V | | | | |
| | | SDA | 3 | - | - | mA |
| | | $\overline{\text{INT}}$ | 3 | 15 ^[2] | - | mA |
| | | P port | | | | |
| | | V _{OL} = 0.5 V; V _{DD} = 1.65 V | ^[3] 8 | 10 | - | mA |
| | | V _{OL} = 0.7 V; V _{DD} = 1.65 V | ^[3] 10 | 13 | - | mA |
| | | V _{OL} = 0.5 V; V _{DD} = 2.3 V | ^[3] 8 | 10 | - | mA |
| | | V _{OL} = 0.7 V; V _{DD} = 2.3 V | ^[3] 10 | 13 | - | mA |
| | | V _{OL} = 0.5 V; V _{DD} = 3.0 V | ^[3] 8 | 14 | - | mA |
| | | V _{OL} = 0.7 V; V _{DD} = 3.0 V | ^[3] 10 | 19 | - | mA |
| V _{OH} | HIGH-level output voltage | P port | | | | |
| | | I _{OH} = -8 mA; V _{DD} = 1.65 V | ^[4] 1.2 | - | - | V |
| | | I _{OH} = -10 mA; V _{DD} = 1.65 V | ^[4] 1.1 | - | - | V |
| | | I _{OH} = -8 mA; V _{DD} = 2.3 V | ^[4] 1.8 | - | - | V |
| | | I _{OH} = -10 mA; V _{DD} = 2.3 V | ^[4] 1.7 | - | - | V |
| | | I _{OH} = -8 mA; V _{DD} = 3.0 V | ^[4] 2.6 | - | - | V |
| | | I _{OH} = -10 mA; V _{DD} = 3.0 V | ^[4] 2.5 | - | - | V |
| | | I _{OH} = -8 mA; V _{DD} = 4.75 V | ^[4] 4.1 | - | - | V |
| I _{OH} = -10 mA; V _{DD} = 4.75 V | ^[4] 4.0 | - | - | V | | |
| I _I | input current | V _{DD} = 1.65 V to 5.5 V | | | | |
| | | SCL, SDA; V _I = V _{DD} or V _{SS} | - | - | 0.1 | μA |
| | | A0, A1, A2; V _I = V _{DD} or V _{SS} | - | - | ±1 | μA |
| I _{IH} | HIGH-level input current | P port; V _I = V _{DD} ; V _{DD} = 1.65 V to 5.5 V | - | - | 1 | μA |
| I _{IL} | LOW-level input current | P port; V _I = V _{SS} ; V _{DD} = 1.65 V to 5.5 V | - | - | -100 | μA |

Table 14. Static characteristics ...continued

$T_{amb} = -40\text{ °C to }+85\text{ °C}$; $V_{DD} = 1.65\text{ V to }5.5\text{ V}$; unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ ^[1] | Max | Unit | |
|-----------------|-------------------------------------|---|-----|--------------------|------|------------------|--|
| I_{DD} | supply current | SDA, P port, A0, A1, A2; V_I on SCL, SDA = V_{DD} or V_{SS} ; V_I on P port and A0, A1, A2 = V_{DD} ; $I_O = 0\text{ mA}$; I/O = inputs; $f_{SCL} = 400\text{ kHz}$ | | | | | |
| | | $V_{DD} = 3.6\text{ V to }5.5\text{ V}$ | - | 10 | 25 | μA | |
| | | $V_{DD} = 2.3\text{ V to }3.6\text{ V}$ | - | 6.5 | 15 | μA | |
| | | $V_{DD} = 1.65\text{ V to }2.3\text{ V}$ | - | 4 | 9 | μA | |
| | | SCL, SDA, P port, A0, A1, A2; V_I on SCL, SDA = V_{DD} or V_{SS} ; V_I on P port and A0, A1, A2 = V_{DD} ; $I_O = 0\text{ mA}$; I/O = inputs; $f_{SCL} = 0\text{ kHz}$ | | | | | |
| | | $V_{DD} = 3.6\text{ V to }5.5\text{ V}$ | - | 1.5 | 7 | μA | |
| | | $V_{DD} = 2.3\text{ V to }3.6\text{ V}$ | - | 1 | 3.2 | μA | |
| | | $V_{DD} = 1.65\text{ V to }2.3\text{ V}$ | - | 0.5 | 1.7 | μA | |
| | | Active mode; P port, A0, A1, A2; V_I on P port and A0, A1, A2 = V_{DD} ; $I_O = 0\text{ mA}$; I/O = inputs; $f_{SCL} = 400\text{ kHz}$, continuous register read | | | | | |
| | | $V_{DD} = 3.6\text{ V to }5.5\text{ V}$ | - | 60 | 125 | μA | |
| | | $V_{DD} = 2.3\text{ V to }3.6\text{ V}$ | - | 40 | 75 | μA | |
| | | $V_{DD} = 1.65\text{ V to }2.3\text{ V}$ | - | 20 | 45 | μA | |
| ΔI_{DD} | additional quiescent supply current | with pull-ups enabled; P port, A0, A1, A2; V_I on SCL, SDA = V_{DD} or V_{SS} ; V_I on P port = V_{SS} ; V_I on A0, A1, A2 = V_{DD} or V_{SS} ; $I_O = 0\text{ mA}$; I/O = inputs with pull-up enabled; $f_{SCL} = 0\text{ kHz}$ | | | | | |
| | | $V_{DD} = 1.65\text{ V to }5.5\text{ V}$ | - | 0.55 | 0.75 | mA | |
| | | SCL, SDA; one input at $V_{DD} - 0.6\text{ V}$, other inputs at V_{DD} or V_{SS} ; $V_{DD} = 1.65\text{ V to }5.5\text{ V}$ | - | - | 25 | μA | |
| | | P port, A0, A1, A2; one input at $V_{DD} - 0.6\text{ V}$, other inputs at V_{DD} or V_{SS} ; $V_{DD} = 1.65\text{ V to }5.5\text{ V}$ | - | - | 80 | μA | |
| C_i | input capacitance | $V_I = V_{DD}$ or V_{SS} ; $V_{DD} = 1.65\text{ V to }5.5\text{ V}$ | - | 6 | 7 | pF | |
| C_{iO} | input/output capacitance | $V_{I/O} = V_{DD}$ or V_{SS} ; $V_{DD} = 1.65\text{ V to }5.5\text{ V}$ | - | 7 | 8 | pF | |
| | | $V_{I/O} = V_{DD}$ or V_{SS} ; $V_{DD} = 1.65\text{ V to }5.5\text{ V}$ | - | 7.5 | 8.5 | pF | |
| $R_{pu(int)}$ | internal pull-up resistance | input/output | 50 | 100 | 150 | $\text{k}\Omega$ | |

- [1] For I_{DD} , all typical values are at nominal supply voltage (1.8 V, 2.5 V, 3.3 V, 3.6 V or 5 V V_{DD}) and $T_{amb} = 25\text{ °C}$. Except for I_{DD} , the typical values are at $V_{DD} = 3.3\text{ V}$ and $T_{amb} = 25\text{ °C}$.
- [2] Typical value for $T_{amb} = 25\text{ °C}$. $V_{OL} = 0.4\text{ V}$ and $V_{DD} = 3.3\text{ V}$. Typical value for $V_{DD} < 2.5\text{ V}$, $V_{OL} = 0.6\text{ V}$.
- [3] Each I/O must be externally limited to a maximum of 25 mA and the device must be limited to a maximum current of 100 mA.
- [4] The total current sourced by all I/Os must be limited to 85 mA.

12.1 Typical characteristics

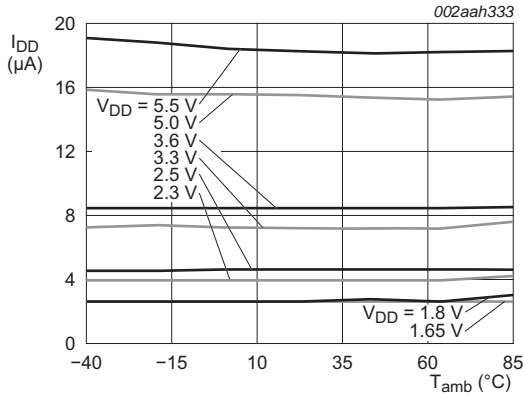


Fig 18. Supply current versus ambient temperature

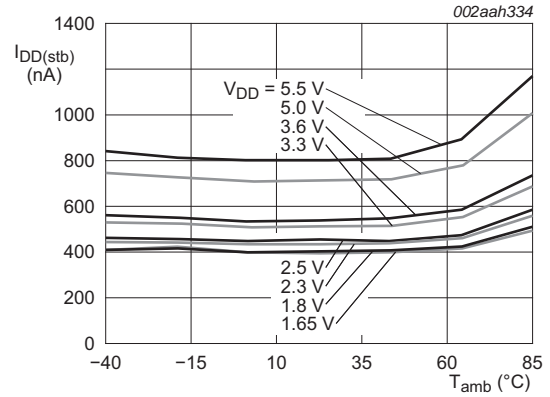


Fig 19. Standby supply current versus ambient temperature

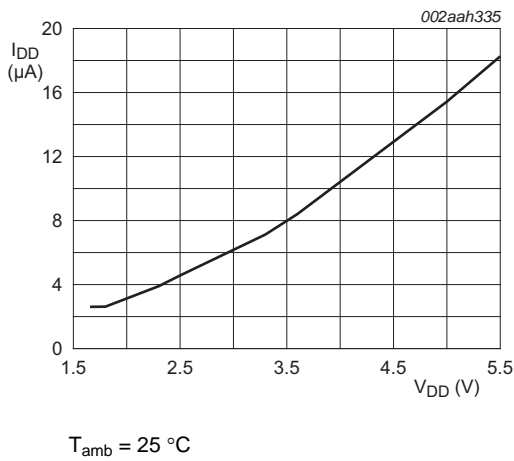


Fig 20. Supply current versus supply voltage

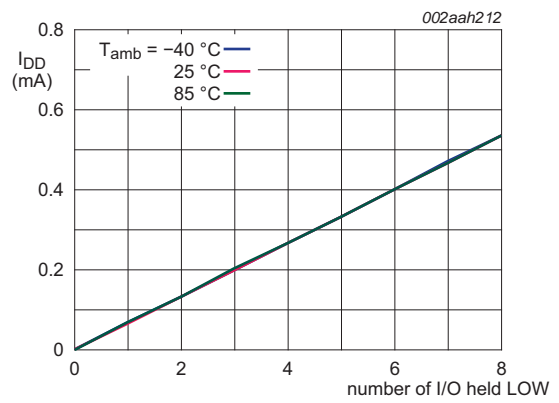
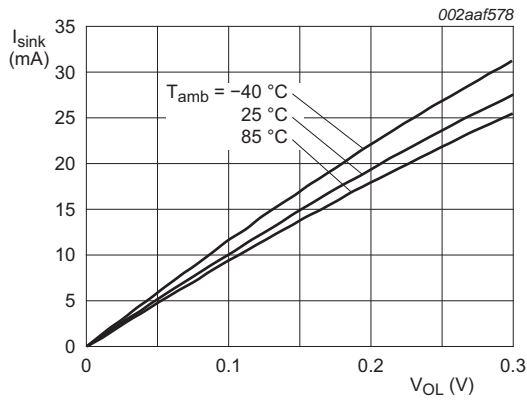
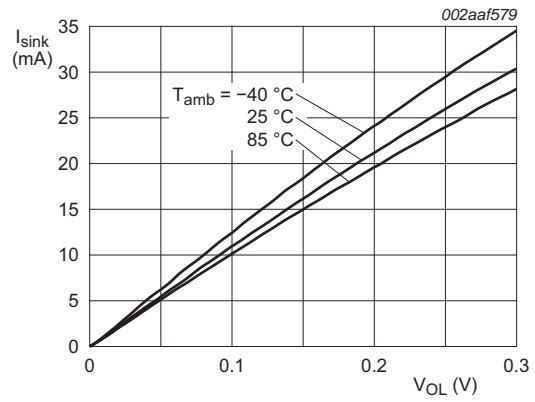


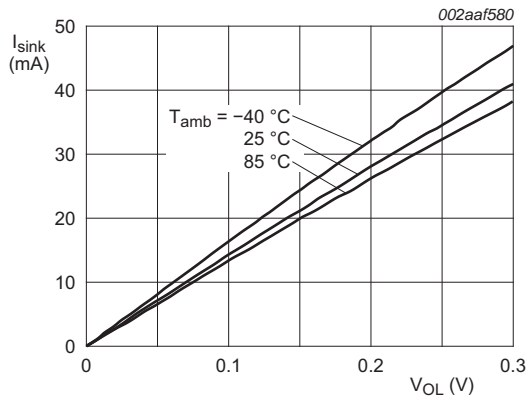
Fig 21. Supply current versus number of I/O held LOW



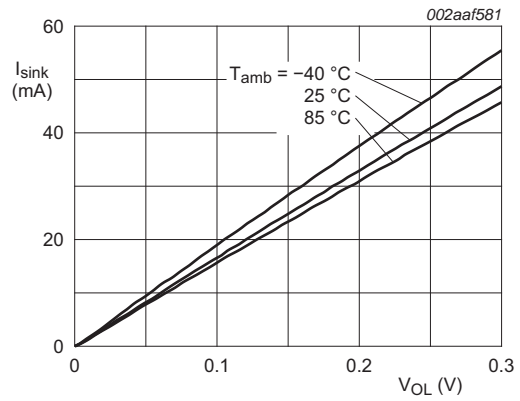
a. $V_{DD} = 1.65\text{ V}$



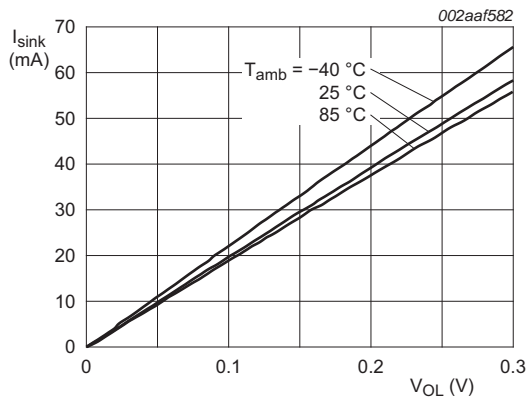
b. $V_{DD} = 1.8\text{ V}$



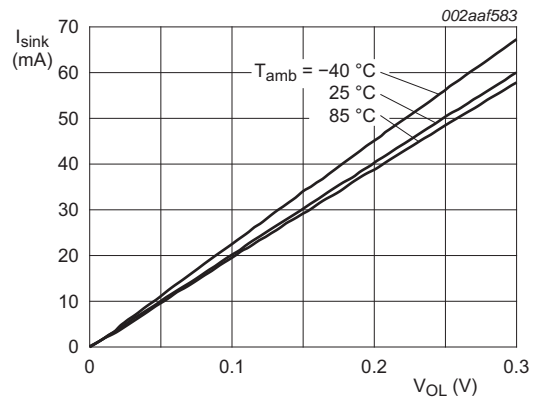
c. $V_{DD} = 2.5\text{ V}$



d. $V_{DD} = 3.3\text{ V}$

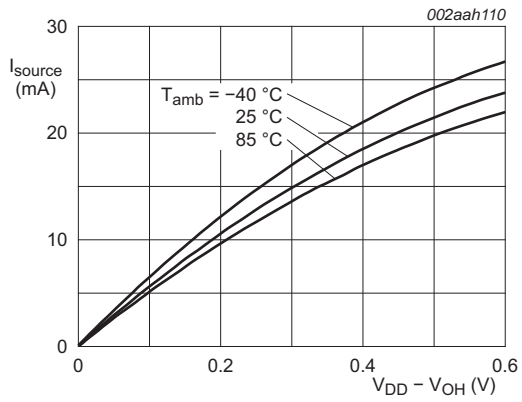


e. $V_{DD} = 5.0\text{ V}$

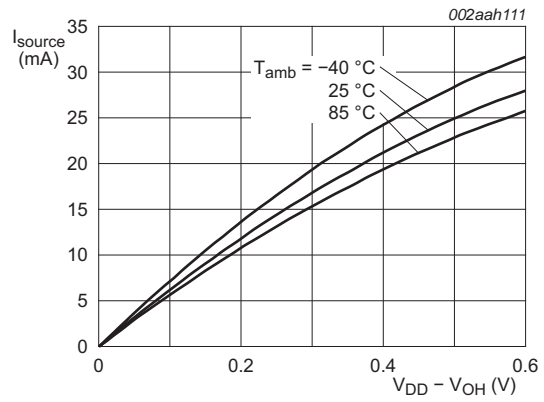


f. $V_{DD} = 5.5\text{ V}$

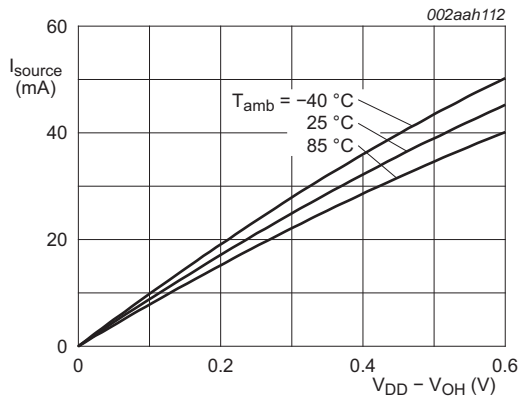
Fig 22. I/O sink current versus LOW-level output voltage



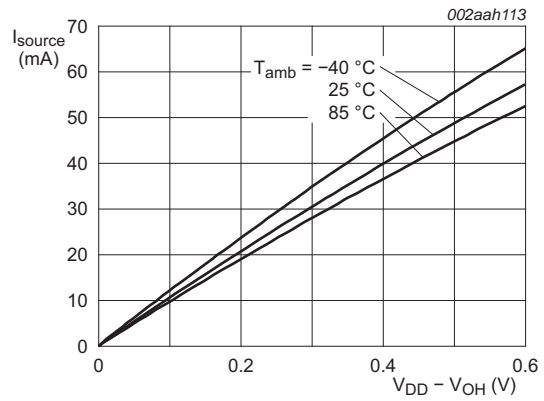
a. $V_{DD} = 1.65\text{ V}$



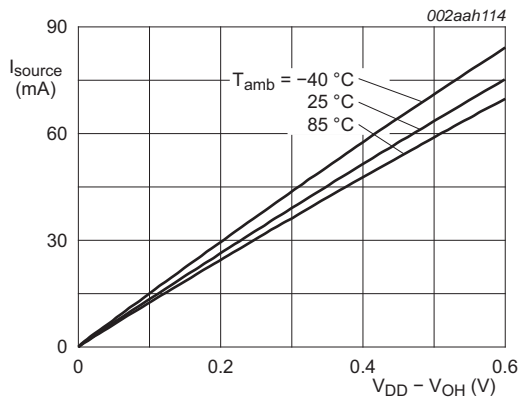
b. $V_{DD} = 1.8\text{ V}$



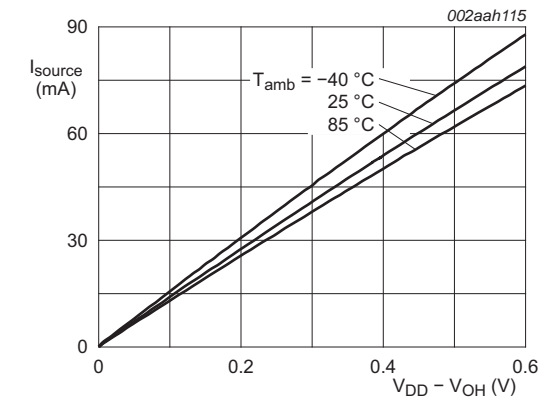
c. $V_{DD} = 2.5\text{ V}$



d. $V_{DD} = 3.3\text{ V}$

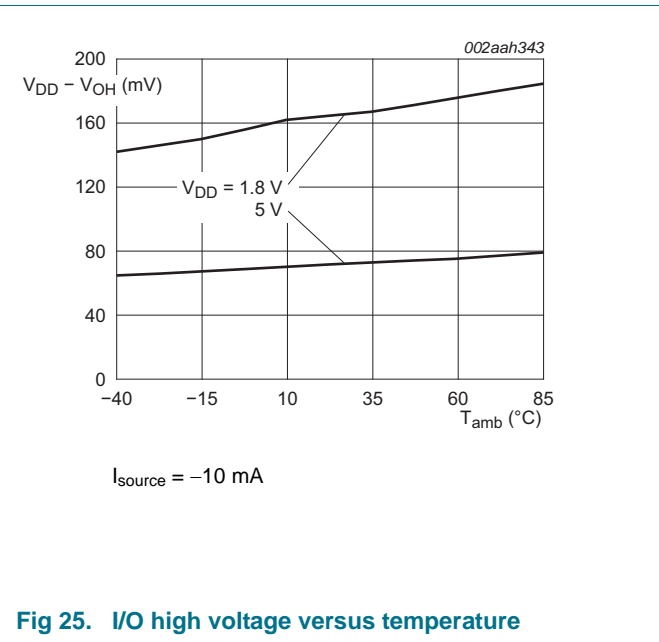
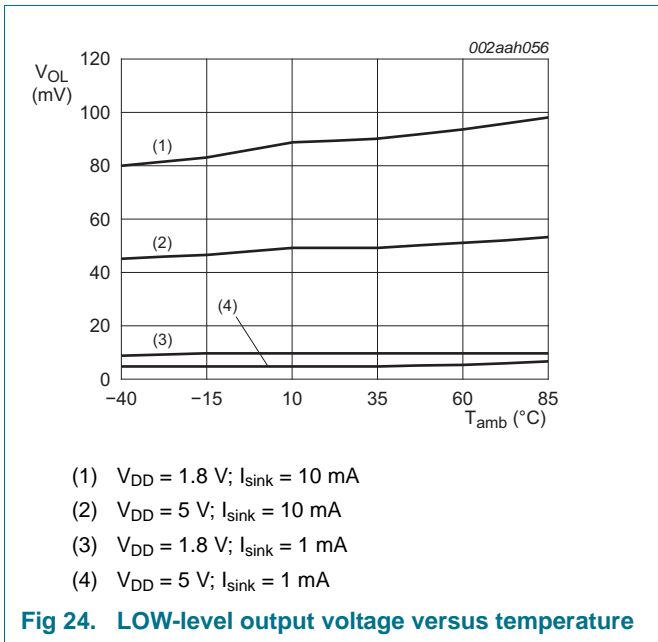


e. $V_{DD} = 5.0\text{ V}$



f. $V_{DD} = 5.5\text{ V}$

Fig 23. I/O source current versus HIGH-level output voltage



13. Dynamic characteristics

Table 15. I²C-bus interface timing requirements

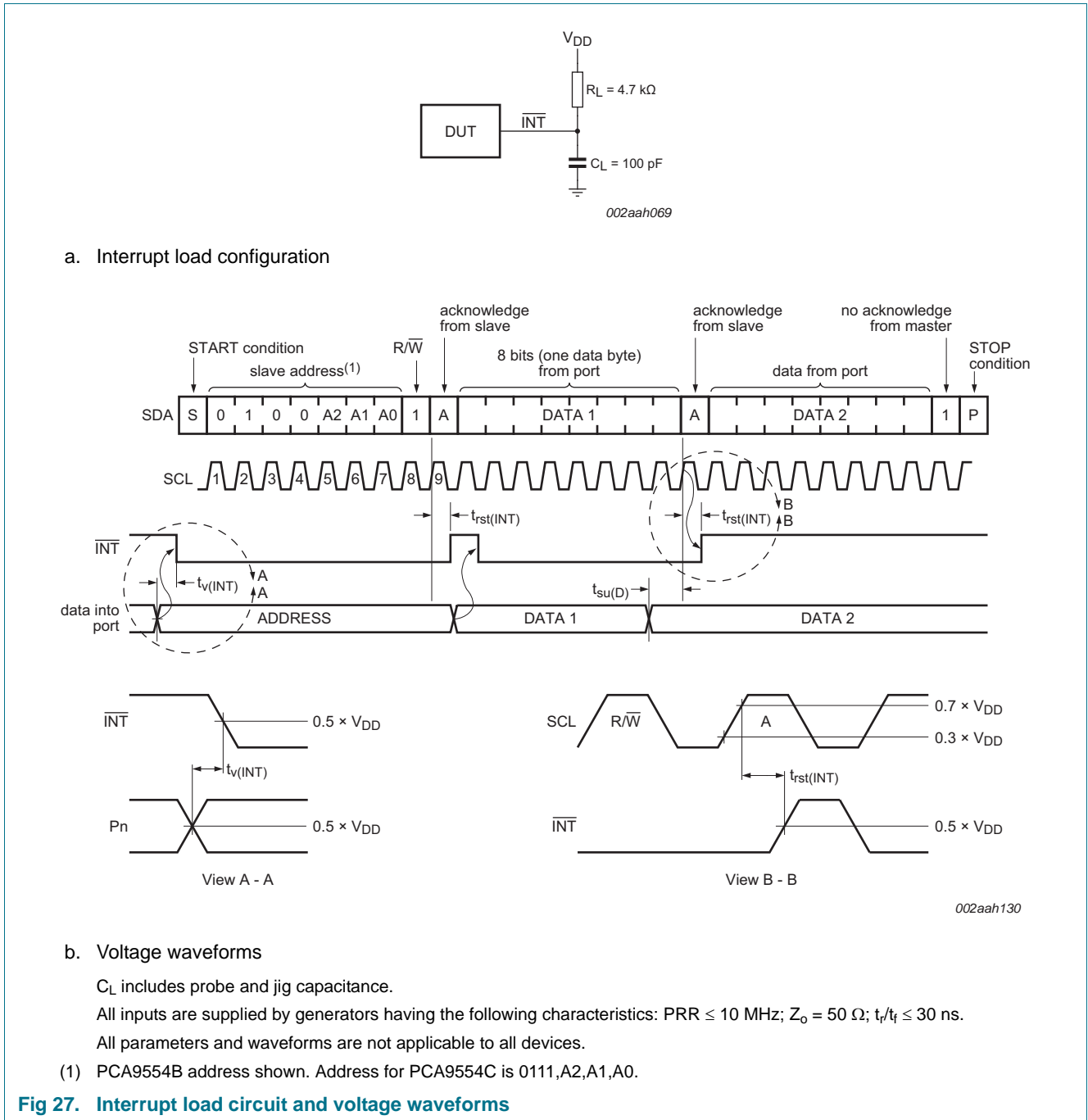
Over recommended operating free air temperature range, unless otherwise specified. See [Figure 26](#).

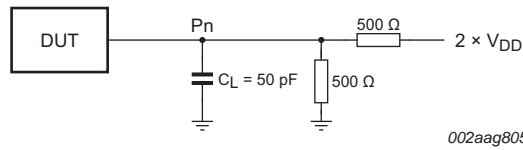
| Symbol | Parameter | Conditions | Standard-mode I ² C-bus | | Fast-mode I ² C-bus | | Unit |
|---------------------|---|--|------------------------------------|------|-----------------------------------|-----|------|
| | | | Min | Max | Min | Max | |
| f _{SCL} | SCL clock frequency | | 0 | 100 | 0 | 400 | kHz |
| t _{HIGH} | HIGH period of the SCL clock | | 4 | - | 0.6 | - | μs |
| t _{LOW} | LOW period of the SCL clock | | 4.7 | - | 1.3 | - | μs |
| t _{SP} | pulse width of spikes that must be suppressed by the input filter | | 0 | 50 | 0 | 50 | ns |
| t _{SU;DAT} | data set-up time | | 250 | - | 100 | - | ns |
| t _{HD;DAT} | data hold time | | 0 | - | 0 | - | ns |
| t _r | rise time of both SDA and SCL signals | | - | 1000 | 20 | 300 | ns |
| t _f | fall time of both SDA and SCL signals | | - | 300 | 20 × (V _{DD} / 5.5 V) | 300 | ns |
| t _{BUF} | bus free time between a STOP and START condition | | 4.7 | - | 1.3 | - | μs |
| t _{SU;STA} | set-up time for a repeated START condition | | 4.7 | - | 0.6 | - | μs |
| t _{HD;STA} | hold time (repeated) START condition | | 4 | - | 0.6 | - | μs |
| t _{SU;STO} | set-up time for STOP condition | | 4 | - | 0.6 | - | μs |
| t _{VD;DAT} | data valid time | SCL LOW to SDA output valid | - | 3.45 | - | 0.9 | μs |
| t _{VD;ACK} | data valid acknowledge time | ACK signal from SCL LOW to SDA (out) LOW | - | 3.45 | - | 0.9 | μs |

Table 16. Switching characteristics

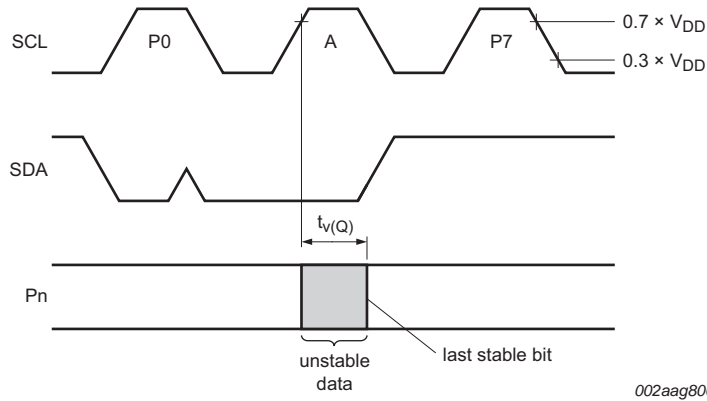
Over recommended operating free air temperature range; C_L ≤ 100 pF; unless otherwise specified. See [Figure 26](#).

| Symbol | Parameter | Conditions | Standard-mode I ² C-bus | | Fast-mode I ² C-bus | | Unit |
|-----------------------|---|--|------------------------------------|-----|--------------------------------|-----|------|
| | | | Min | Max | Min | Max | |
| t _{V(INT)} | valid time on pin $\overline{\text{INT}}$ | from P port to $\overline{\text{INT}}$ | - | 1 | - | 1 | μs |
| t _{rst(INT)} | reset time on pin $\overline{\text{INT}}$ | from SCL to $\overline{\text{INT}}$ | - | 1 | - | 1 | μs |
| t _{V(Q)} | data output valid time | from SCL to P port | - | 400 | - | 400 | ns |
| t _{SU(D)} | data input set-up time | from P port to SCL | 0 | - | 0 | - | ns |
| t _{h(D)} | data input hold time | from P port to SCL | 300 | - | 300 | - | ns |

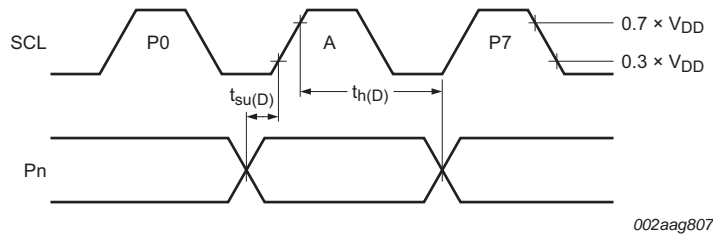




a. P port load configuration



b. Write mode ($\overline{R/\overline{W}} = 0$)



c. Read mode ($\overline{R/\overline{W}} = 1$)

C_L includes probe and jig capacitance.

$t_{V(Q)}$ is measured from $0.7 \times V_{DD}$ on SCL to 50 % I/O (P_n) output.

All inputs are supplied by generators having the following characteristics: PRR \leq 10 MHz; $Z_o = 50 \Omega$; $t_r/t_f \leq 30$ ns.

The outputs are measured one at a time, with one transition per measurement.

All parameters and waveforms are not applicable to all devices.

Fig 28. P port load circuit and voltage waveforms

15. Package outline

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

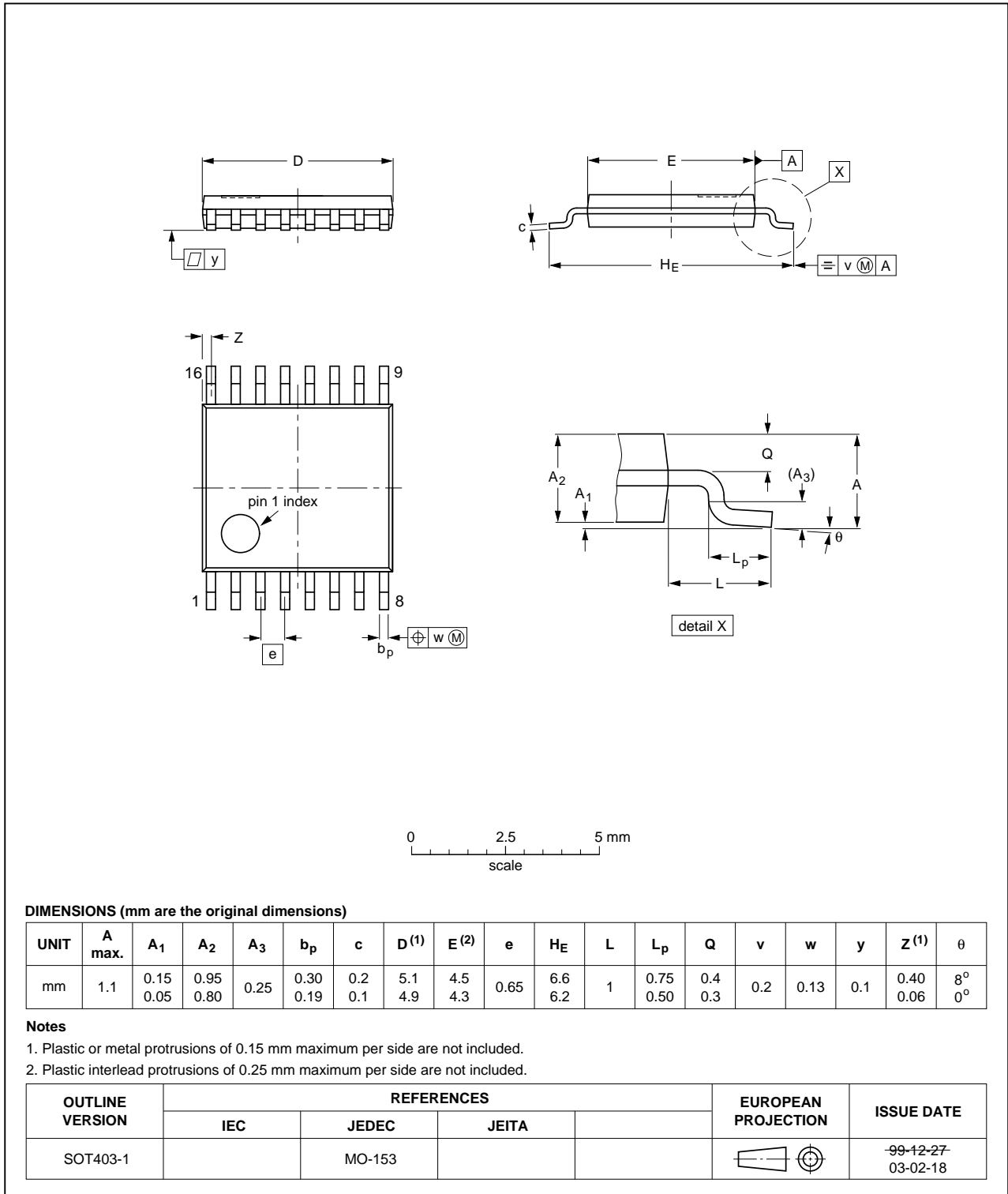


Fig 29. Package outline SOT403-1 (TSSOP16)

HVQFN16: plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm

SOT758-1

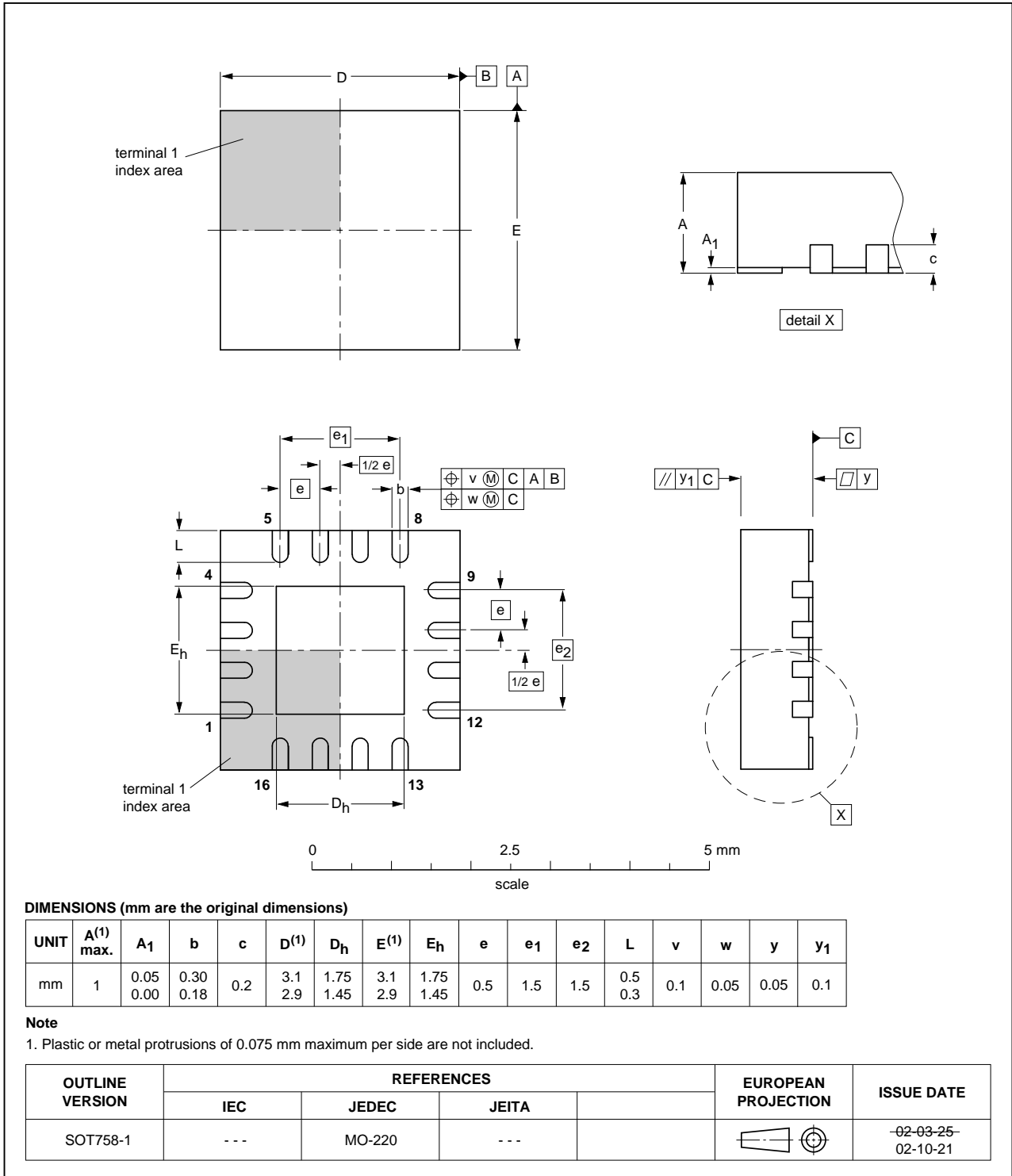


Fig 30. Package outline SOT758-1 (HVQFN16)

16. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

17. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

17.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

17.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

17.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

17.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 31](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 17](#) and [18](#)

Table 17. SnPb eutectic process (from J-STD-020C)

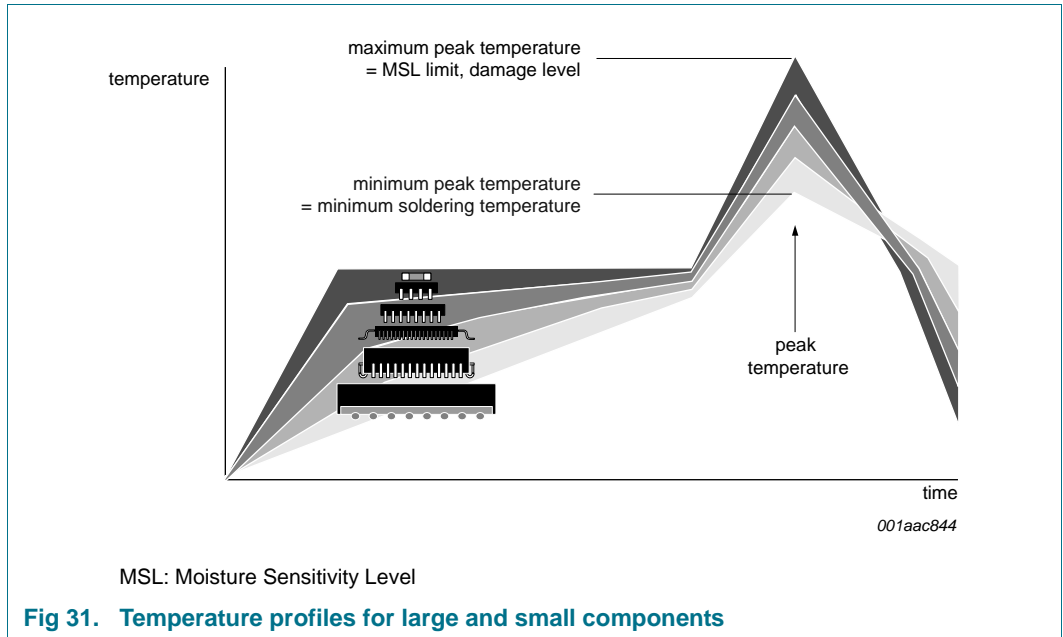
| Package thickness (mm) | Package reflow temperature (°C) | |
|------------------------|---------------------------------|-------|
| | Volume (mm ³) | |
| | < 350 | ≥ 350 |
| < 2.5 | 235 | 220 |
| ≥ 2.5 | 220 | 220 |

Table 18. Lead-free process (from J-STD-020C)

| Package thickness (mm) | Package reflow temperature (°C) | | |
|------------------------|---------------------------------|-------------|--------|
| | Volume (mm ³) | | |
| | < 350 | 350 to 2000 | > 2000 |
| < 1.6 | 260 | 260 | 260 |
| 1.6 to 2.5 | 260 | 250 | 245 |
| > 2.5 | 250 | 245 | 245 |

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 31](#).

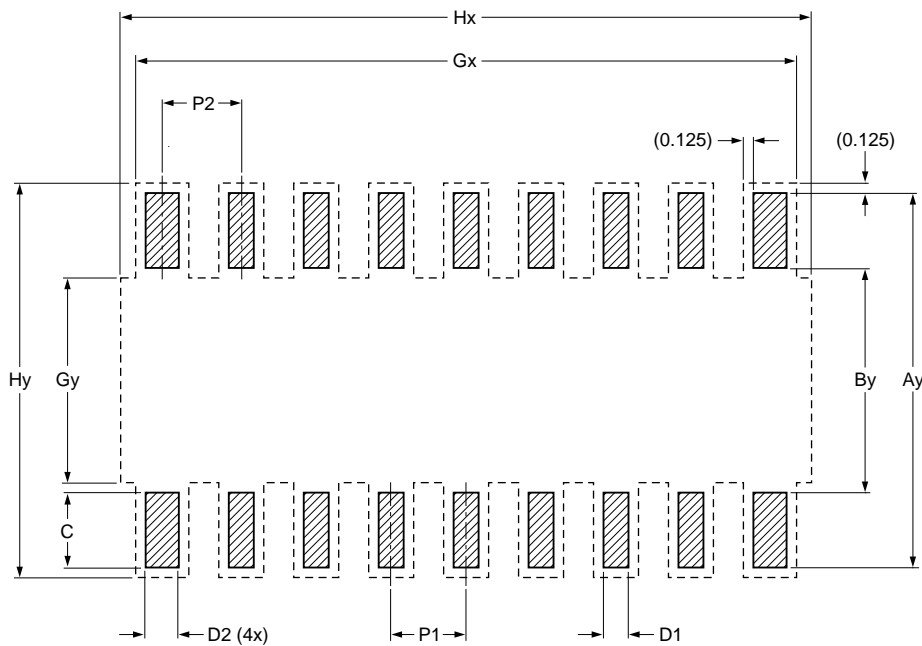


For further information on temperature profiles, refer to Application Note AN10365 “Surface mount reflow soldering description”.


18. Soldering: PCB footprints

Footprint information for reflow soldering of TSSOP16 package

SOT403-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

| P1 | P2 | Ay | By | C | D1 | D2 | Gx | Gy | Hx | Hy |
|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|
| 0.650 | 0.750 | 7.200 | 4.500 | 1.350 | 0.400 | 0.600 | 5.600 | 5.300 | 5.800 | 7.450 |

sot403-1_fr

Fig 32. PCB footprint for SOT403-1 (TSSOP16); reflow soldering

Footprint information for reflow soldering of HVQFN16 package

SOT758-1

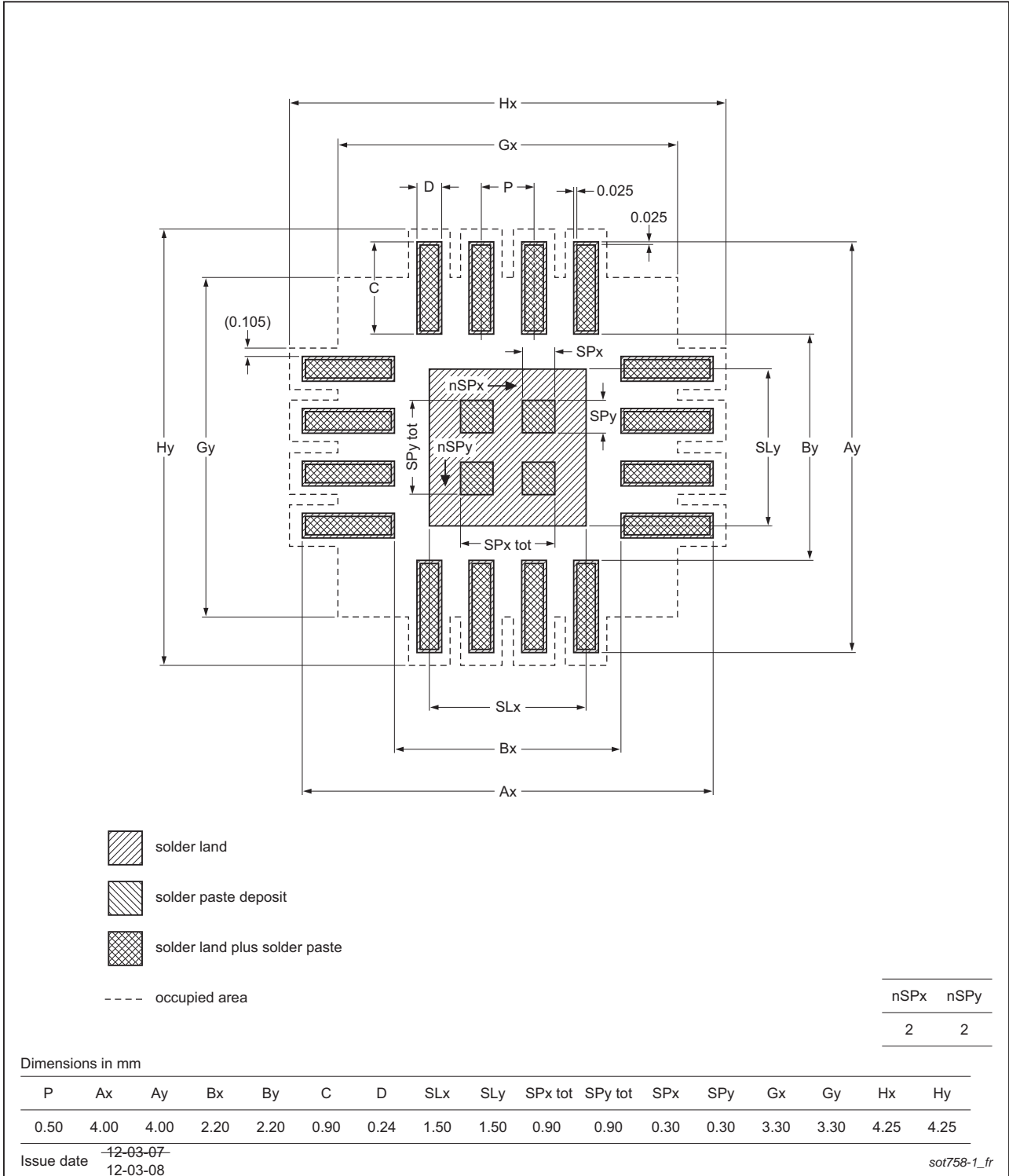


Fig 33. PCB footprint for SOT758-1 (HVQFN16); reflow soldering

19. Abbreviations

Table 19. Abbreviations

| Acronym | Description |
|----------------------|--|
| ACPI | Advanced Configuration and Power Interface |
| CBT | Cross-Bar Technology |
| CDM | Charged-Device Model |
| CMOS | Complementary Metal-Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| FET | Field-Effect Transistor |
| FF | Flip-Flop |
| GPIO | General Purpose Input/Output |
| HBM | Human Body Model |
| I ² C-bus | Inter-Integrated Circuit bus |
| I/O | Input/Output |
| LED | Light Emitting Diode |
| LP | Low-Pass |
| LSB | Least Significant Bit |
| MSB | Most Significant Bit |
| PCB | Printed-Circuit Board |
| POR | Power-On Reset |
| SCR | Silicon Controlled Rectifier |
| SMBus | System Management Bus |

20. Revision history

Table 20. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-----------------------|--------------|--------------------|---------------|------------|
| PCA9554B_PCA9554C v.1 | 20120919 | Product data sheet | - | - |

21. Legal information

21.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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